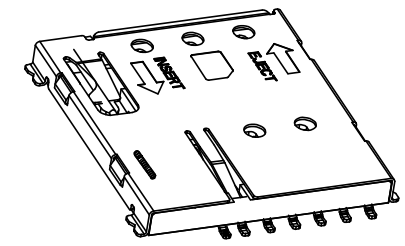
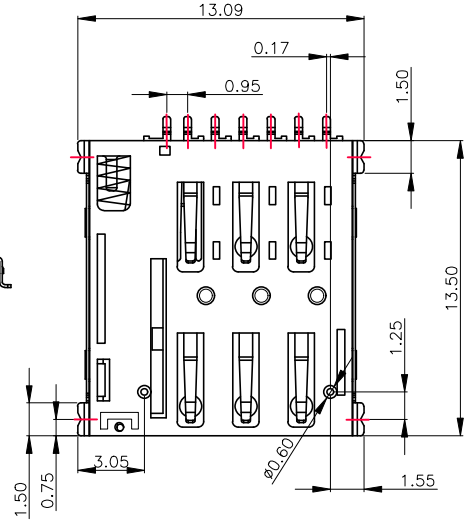
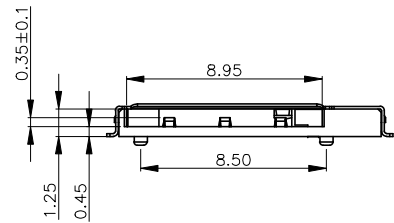
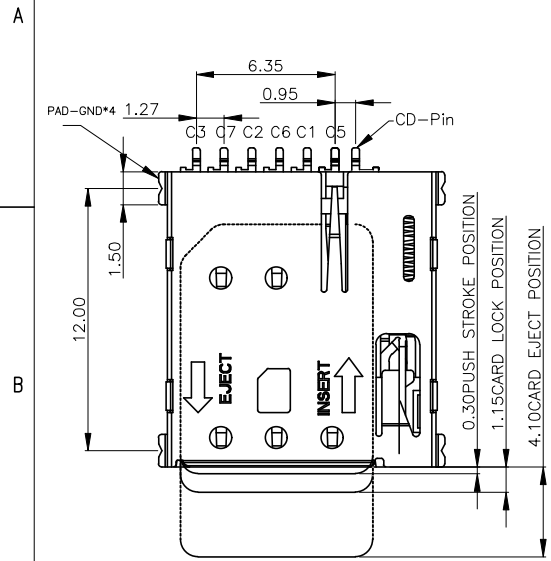




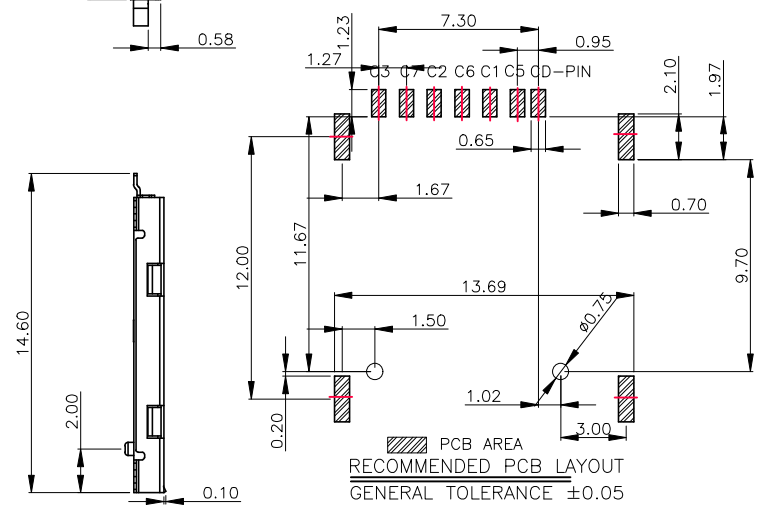
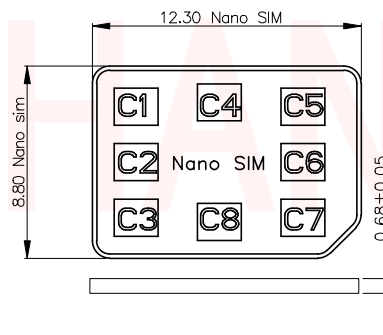
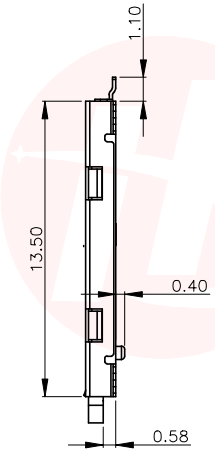
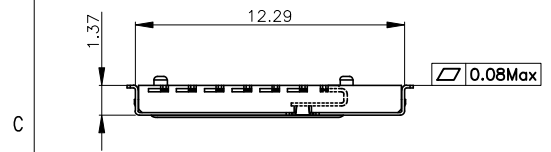
REV.	ECN NO OR DESCRIPTION	REVISED	DATE



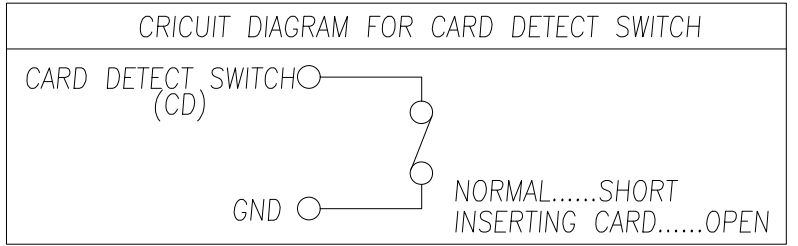
Specification

MATERIAL:
 Insulator: High Temperature Thermoplastic, UL 94V-0.
 Contact: Copper Alloy
 SHELL: SUS
 PLATING:
 Contact: ALL AU GOLD 1U
 Shell: Plated 50u" Ni Overall, PAD Au 1U

Electrical:
 Current Rating :0.5mA AC/DC max.
 Voltage Rating :125V AC/DC
 Ambient Temperature Range :-20°C~+60°C
 Storage Temperature Range :-40°C~+70°C
 Ambient Humidity Range :95% R.H. Max.
 Contact Resistance:100Ω m max.
 Insulation Resistance:1000M Ω min./500VDC
 Mating Cycles:3000 Insertions
 产品耐温温度:260度



PCB AREA RECOMMENDED PCB LAYOUT GENERAL TOLERANCE ±0.05



SIM pin assignment	
PIN#	Name
C1	VCC供电电压
C2	RST重置
C3	CLK时钟
C5	GND接地
C6	VPP程序电压
C7	I/O输入输出

UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD			
DECIMALS:	ANGLES:	TITLE	NANO SIM 卡座 PUSH/PUSH 1.35H 带CD PIN		
X :±0.15	X :±2°	DWN	xiong	PART NO. SNO-1350	
X.X :±0.10	X.X :±1°	CHKD	lee	SCALE:1:1	UNIT: mm
X.XX :±0.05		APVD	wang	SIZE: A4	SHEET:10F 1
					REV: A4
				CUSTOMER COPY	